

EMBOSSING PROCESSES FOR SUBSTRATE IMPRINTING,
STRUCTURES MADE THEREBY,
AND POLYMERS USED THEREFOR

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ABSTRACT OF THE DISCLOSURE

A mounting substrate includes an imprinted structure on one side for
containing electrical bumps. The imprinted structure is imprinted and also cured
under conditions that allow retention of significant features of the cured polymer
10 film. A chip package is also made of the imprinted structure. A computing system
is also disclosed that includes the imprinted structure.

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